



SECT. B-B

SECT. A-A

NOTES.

- 適合ハウジング: 501330-**** / 501939-****
APPLICABLE HOUSING: 501330-**** / 501939-****
- メッキ仕様
PLATING
錫メッキ: 1.0μmMIN. リフロー処理(前メッキ)
Sn: 1.0μmMIN. REFLOW TREATMENT (PRE-PLATED)
- 刻印は裏面から実施
PUNCH SIDE: OTHER SIDE
MXJ 金型番号(番号無しの製品もあります.)
Die No. (There is Non-Mark Item)
TREAD MARK

501334-0100	バラ状 LOOSE
501334-0000	連鎖状 CHAIN
MATERIAL NO.	端子形状 FORM

MATERIAL リン青銅 PHOSPHOR BRONZE t=0.12	REVISED EC NO.: J2009-0651 DRW: NAKATA 2008/09/16 CHK: MATSUMOTO 2008/09/16 APP: NUKITA 2008/09/16	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
FINISH SEE NOTE		10 UNDER ±0.2	DRAWN BY NYOSHIDA	DATE 2004/07/29	TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL (SN) -LEAD FREE-	
WIRE RANGE AWG #28-32		10 OVER 30 UNDER ±0.25	CHECKED BY MYAGI	DATE 2004/07/29	MOLEX INCORPORATED	
INS. RANGE φ0.4-0.8		30 OVER ±0.3	APPROVED BY MIYAZAWA	DATE 2004/07/29	DOCUMENT NO. SD-501334-001	SHEET NO. 1 OF 1
		ANGULAR ±3°	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3			